

L Number	Hits	Search Text	DB	Time stamp
1	0	heat\$lindicat\$3 adj (paint strip)	USPAT; EPO; JPO	2003/10/18 11:13
2	4	(heat adj indicat\$3 heat\$lindicat\$3) adj (paint strip)	USPAT; EPO; JPO	2003/10/18 11:15
3	3	heat adj indicat\$3 with (paint strip material) and heat\$3 and substrate and circuit	USPAT; EPO; JPO	2003/10/18 11:18
4	0	heat adj indicator and temperature and anneal and heat\$3 and substrate and circuit	USPAT; EPO; JPO	2003/10/18 11:19
5	23	heat\$3 adj1 indicator and temperature and substrate and circuit	USPAT; EPO; JPO	2003/10/18 11:23
6	19	("4028118" "4032687" "4142782" "4360780" "4379816" "4497881" "4702563" "4702564" "4725462" "4726661" "4727006" "4737020" "4835475" "4835476" "5015544" "5059895" "5156931" "5371657" "5466654").PN.	USPAT	2003/10/18 11:20
7	109542	(temperature heat\$3 adj1 indicator) and temperature and substrate and circuit	USPAT; EPO; JPO	2003/10/18 11:24
8	201	(temperature heat\$3) adj1 indicator and temperature and substrate and circuit	USPAT; EPO; JPO	2003/10/18 11:27
9	24	((temperature heat\$3) adj1 indicator and temperature and substrate and circuit) and anneal\$3	USPAT; EPO; JPO	2003/10/18 11:24
10	7	(temperature heat\$3) adj1 indicator with (paint\$3 strip) and temperature and substrate and circuit	USPAT; EPO; JPO	2003/10/18 12:43
13	1	(temperature heat\$3) adj1 indicator with (paint\$3 strip) and substrate and circuit and (oven furnace)	USPAT; EPO; JPO	2003/10/18 12:44
14	15	(temperature heat\$3) adj1 indicator with (paint\$3 strip) and substrate and (oven furnace)	USPAT; EPO; JPO	2003/10/18 13:32
15	4	5340537.URPN.	USPAT	2003/10/18 13:21
16	11	(temperature heat\$3) adj1 indicator with (paint\$3 strip) and surface with substrate and (oven furnace)	USPAT; EPO; JPO	2003/10/18 13:32
-	2	heating with microelectronic.ti.	USPAT; US-PGPUB	2003/09/20 11:19
-	18	heating and microelectronic and oscillat\$3 with electro\$l magnetic and field	USPAT; EPO; JPO	2003/09/20 11:21
-	26	heat\$3 and microelectronic and oscillat\$3 with electro\$l magnetic and field	USPAT; EPO; JPO	2003/09/20 11:24
-	92	heat\$3 with oscillat\$3 with electro\$l magnetic with field	USPAT; EPO; JPO	2003/09/20 11:24
-	3	"6150186"	USPAT	2003/09/20 14:35
-	100	"5476211"	USPAT	2003/09/20 14:39
-	51	"5917707"	USPAT	2003/09/20 14:40
-	8	"6336269"	USPAT	2003/09/20 14:40
-	272	micro\$lelectronic and heat\$3 and cool\$3 and oscillat\$3	USPAT; EPO; JPO	2003/10/15 19:06
-	95	(micro\$lelectronic and heat\$3 and cool\$3 and oscillat\$3) and electro\$l magnetic	USPAT; EPO; JPO	2003/10/15 19:07
-	95	29/\$.ccls. and 219/\$.ccls. and 148/\$.ccls.	USPAT; EPO; JPO	2003/10/16 13:48
-	41	(29/\$.ccls. and 219/\$.ccls. and 148/\$.ccls.) and heat\$3	USPAT; EPO; JPO	2003/10/16 13:49
-	3	((29/\$.ccls. and 219/\$.ccls. and 148/\$.ccls.) and heat\$3) and electro\$l magnetic	USPAT; EPO; JPO	2003/10/16 13:50

-	3	((29/\$.ccls. and 219/\$.ccls. and 148/\$.ccls.) and heat\$3) and oscillat\$3	USPAT;	2003/10/16
-	4	((29/\$.ccls. and 219/\$.ccls. and 148/\$.ccls.) and heat\$3) and wave	EPO; JPO	13:51
-	448	(heat\$1treatment heat adj1 treatment) and electromagnetic adj field	USPAT;	2003/10/16
-	305	((heat\$1treatment heat adj1 treatment) and electromagnetic adj field) and frequency	EPO; JPO	13:54
-	64	((heat\$1treatment heat adj1 treatment) and electromagnetic adj field) and frequency) and cool\$3 and substrate	USPAT;	2003/10/16
-	466	(heat\$1treatment heat adj1 treatment) and electromagnetic adj field	EPO; JPO	14:17
-	39	(electro\$magnetic adj field) and (heat\$1treatment heat adj1 treatment) and (electromagnetic adj field) and electro\$magnetic adj field)) and generat\$3 and resonant adj frequency	USPAT;	2003/10/16
-	124	oscillating adj electromagnetic adj field and heat\$3	EPO; JPO	13:56
-	4	(oscillating adj electromagnetic adj field and heat\$3) and micro\$electronic	USPAT;	2003/10/16
-	898	heat\$3 and cool\$3 and micro\$electronic and substrate and frequency and temperature	EPO; JPO	14:16
-	429	heat\$3 and cool\$3 and micro\$electronic and substrate and frequency and metallic and temperature	USPAT;	2003/10/16
-	75	(heat\$3 and cool\$3 and micro\$electronic and substrate and frequency and metallic and temperature) and oven	EPO; JPO	2003/10/16
-	55	(oscillating adj electromagnetic adj field and heat\$3) and cool\$3 and temperature	USPAT;	14:18
-	151	(heat\$3 and cool\$3 and micro\$electronic and substrate and frequency and metallic and temperature) and microwave	EPO; JPO	2003/10/16
-	4	("2903543" "4522834" "4974503" "4980530").PN.	USPAT;	15:09
-	2	("4978501" "5035858").PN.	USPAT;	2003/10/16
-	4	("4422442" "4801343" "5047605" "5994680").PN.	EPO; JPO	15:10
-	435	micro\$electronic and anneal\$3 and (electro\$magnetic microwave)	USPAT;	2003/10/16
-	256	micro\$electronic and anneal\$3 and (electro\$magnetic microwave) and frequency	EPO; JPO	15:11
-	59	(micro\$electronic and anneal\$3 and (electro\$magnetic microwave) and frequency) and spring	USPAT;	2003/10/16
-	68	(micro\$electronic and anneal\$3 and (electro\$magnetic microwave) and frequency) and resonant	EPO; JPO	15:38
-	235	148/525,565.ccls. and heat\$3 and cool\$3	USPAT;	2003/10/16
-	1	(148/525,565.ccls. and heat\$3 and cool\$3) and micro\$electronic	EPO; JPO	15:08
-	36	148/525,565.ccls. and heat\$3 and electro\$magnetic	USPAT;	2003/10/16
-	6	("2491134" "3615924" "3660630" "4181845" "4312685" "4420346").PN.	EPO; JPO	15:09
-	8	4872926.URPN.	USPAT;	2003/10/16
-	205	219/602,605,615,616,632,635,636,764,765,770 and heat\$3 and electro\$magnetic	EPO; JPO	15:11
-	0	(219/602,605,615,616,632,635,636,764,765,770 and heat\$3 and electro\$magnetic) and micro\$electronic	USPAT;	2003/10/16

-	151	(219/602,605,615,616,632,635,636,764,765,770) and heat\$3 and electro\$lmagnetic) and frequency) and tun\$3	USPAT; EPO; JPO	2003/10/16 18:12
-	39	(219/602,605,615,616,632,635,636,764,765,770) and heat\$3 and electro\$lmagnetic) and frequency) and tun\$3	USPAT; EPO; JPO	2003/10/16 18:12
-	0	29/dig13.ccls. and heat\$3 and electro\$lmagnetic	USPAT; EPO; JPO	2003/10/16 18:17
-	0	29/dig21.ccls. and heat\$3 and electro\$lmagnetic	USPAT; EPO; JPO	2003/10/16 18:17
-	24	29/dig\$.ccls. and heat\$3 and electro\$lmagnetic	USPAT; EPO; JPO	2003/10/16 18:20
-	9	29/dig\$.ccls. and heat\$3 and microwave	USPAT; EPO; JPO	2003/10/16 19:42
-	1566	156/\$.ccls. and heat\$3 and microwave	USPAT; EPO; JPO	2003/10/16 19:50
-	78	(156/\$.ccls. and heat\$3 and microwave) and microelectronic	USPAT; EPO; JPO	2003/10/16 19:43
-	68	((156/\$.ccls. and heat\$3 and microwave) and microelectronic) and frequency	USPAT; EPO; JPO	2003/10/16 19:43
-	31	((156/\$.ccls. and heat\$3 and microwave) and microelectronic) and frequency) and electro\$lmagnetic	USPAT; EPO; JPO	2003/10/16 19:44
-	10	156/\$.ccls. and heat\$3 and electro\$lmagnetic and anneal\$3 and cool\$3 and metallic adj material	USPAT; EPO; JPO	2003/10/16 20:09
-	39	electromagnetic and anneal\$3 and heat\$3 with treat\$4 and frequency and resonant and tun\$4	USPAT; EPO; JPO	2003/10/16 20:14
-	30	(electromagnetic and anneal\$3 and heat\$3 with treat\$4 and frequency and resonant and tun\$4) and (device structure)	USPAT; EPO; JPO	2003/10/16 20:11
-	925595	electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 frequency	USPAT; EPO; JPO	2003/10/16 20:15
-	67	electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 and frequency	USPAT; EPO; JPO	2003/10/16 20:41
-	614	electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4	USPAT; EPO; JPO	2003/10/16 20:42
-	44	(electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4) and metallic adj material	USPAT; EPO; JPO	2003/10/16 20:42
-	2456	inductive adj heating	USPAT; EPO; JPO	2003/10/17 10:00
-	23	(inductive adj heating) and micro\$lelectronic	USPAT; EPO; JPO	2003/10/17 10:04
-	0	(inductive adj heating) and non\$lmetallic adj substrate	USPAT; EPO; JPO	2003/10/17 10:05
-	0	(inductive adj heating) and hairpin adj coil	USPAT; EPO; JPO	2003/10/17 10:05
-	0	(inductive adj heating) and hair\$lpin adj coil	USPAT; EPO; JPO	2003/10/17 10:05
-	99	(inductive adj heating) and resonant adj frequency	USPAT; EPO; JPO	2003/10/17 10:06
-	22	((inductive adj heating) and resonant adj frequency) and ferromagnetic	USPAT; EPO; JPO	2003/10/17 10:11
-	231	(inductive adj heating) and electromagnetic adj field	USPAT; EPO; JPO	2003/10/17 10:12
-	50	((inductive adj heating) and electromagnetic adj field) and heat\$3 and substrate	USPAT; EPO; JPO	2003/10/17 10:25

-	145	("1566500" "2378801" "2429819" "2549930" "3272954" "3466528" "3562054" "3574031" "3609104" "3612803" "3657038" "3671371" "3710062" "3733231" "3737611" "3743808" "3746825" "3816690" "3823362" "3833439" "3845268" "3846204" "3902940" "3953700" "3953783" "3996402" "4017701" "4018642" "4029837" "4038120" "4112286" "4120712" "4123305" "4177494" "4234824" "4268737" "4277667" "4280038" "4293363" "4327268" "4355222" "4382275" "4410457" "4420876" "4467165" "4481709" "4483896" "4506131" "4511956" "4516104" "4521659" "4528057" "4543555" "4567094" "4578553" "4581158" "4602139" "4637199" "4650947" "4654495" "4668851" "4677535" "4707402" "4749833" "4762864" "4763093" "4769519" "4776980" "4816633" "4841706" "4845332" "4847746" "4853832" "4897518" "4941936" "4950348" "4969968" "RE33467" "4978825" "4983804" "5025123" "5030816" "5031088" "5057370" "5075034" "5093545" "5123989" "5124203" "5128504" "5134000" "5134261" "5170025" "5198053" "5222185" "5225287" "5266764" "5272216" "5286941" "5286952" "5298194" "5313034" "5313037" "5317045" "5328539" "5340428" "5343023" "5350902" "5374808" "5374809" "5376403" "5378879" "5391595" "5438181" "5483043" "5490759" "5500511" "5504309" "5508496" "5534097" "5573613" "5639847" "5705796" "5710413" "5717191" "5723849" "5773799" "5799653" "5830389" "5837088" "5874713" "5877552" "5916469" "5919387" "5925455" "5932057" "5935369" "6043471" "6056844" "RE36787" "6083558" "6100696" "6110565" "6137093" "6229127" "6302178").PN.	USPAT	2003/10/17 10:13
-	73	((inductive adj heating) and electromagnetic adj field) and heat\$3 with (electronic circuit)	USPAT; EPO; JPO	2003/10/17 10:39
-	6	((inductive adj heating) and electromagnetic adj field) and heat\$3 with electronic with (device circuit)	USPAT; EPO; JPO	2003/10/17 10:49
-	9	4996405.URPN.	USPAT	2003/10/17 10:40
-	26	((inductive adj heating) and electromagnetic adj field) and heat\$3 adj treat\$4	USPAT; EPO; JPO	2003/10/17 10:52
-	221	microelectronic with structure and heat\$3 adj treat\$4	USPAT; EPO; JPO	2003/10/17 10:53
-	207	(microelectronic with structure and heat\$3 adj treat\$4) and substrate	USPAT; EPO; JPO	2003/10/17 10:53
-	84	((microelectronic with structure and heat\$3 adj treat\$4) and substrate) and metallic	USPAT; EPO; JPO	2003/10/17 10:53
-	68	((microelectronic with structure and heat\$3 adj treat\$4) and substrate) and metallic) and insulat\$4	USPAT; EPO; JPO	2003/10/17 10:54

-	11	("2762892" "3467806" "4327265" "4431891" "4642442" "4659912" "4749833" "4771151" "4789767" "4795870" "4806107").PN.	USPAT	2003/10/17 14:33
-	18	4983804.URPN.	USPAT	2003/10/17 14:35
-	25	4969968.URPN.	USPAT	2003/10/17 14:40
-	554	heat\$3 and heat\$3 adj treat\$4 and micro\$electronic and cool\$3	USPAT; US-PGPUB; EPO; JPO	2003/10/17 16:03
-	174	(heat\$3 and heat\$3 adj treat\$4 and micro\$electronic and cool\$3) and substrate and metallic	USPAT; US-PGPUB; EPO; JPO	2003/10/17 16:03
-	45	((heat\$3 and heat\$3 adj treat\$4 and micro\$electronic and cool\$3) and substrate and metallic) and (electromagnetic oscillat\$4)	USPAT; US-PGPUB; EPO; JPO	2003/10/17 16:12
-	0	heat\$3 and cool\$3 and (electromagnetic oscillat\$4) with field and electronic with component with heat\$3 with treat\$4	USPAT; EPO; JPO	2003/10/17 16:14
-	14	heat\$3 and cool\$3 and (electromagnetic oscillat\$4) with field and electronic with heat\$3 with treat\$4	USPAT; EPO; JPO	2003/10/17 16:14
-	22	("3725629" "3946349" "4160967" "4222023" "4296295" "4549056" "4950348" "5101086" "5208433" "5319179" "5343023" "5352871" "5412184" "5461215" "5466916" "5504309" "5526561" "5714738" "5721413" "5739506" "5773799" "5919387").PN.	USPAT	2003/10/17 16:58
-	1	6229126.URPN.	USPAT	2003/10/17 16:38
-	0	4503306.URPN.	USPAT	2003/10/17 16:53
-	0	4503306.URPN.	USPAT	2003/10/17 16:53
-	16	microelectronic and heat\$3 adj treat\$4 and spring with structure	USPAT; EPO; JPO	2003/10/17 17:11
-	316	microelectronic and heat\$3 adj treat\$4 and oven	USPAT; EPO; JPO	2003/10/17 17:11
-	210	microelectronic and heat\$3 adj treat\$4 and (oven furnace) and metallic	USPAT; EPO; JPO	2003/10/17 17:13
-	8	microelectronic and heat\$3 adj treat\$4 and inductive with heat\$3	USPAT; EPO; JPO	2003/10/17 18:03
-	9	electromagnetic adj field and heat\$3 adj treat\$4 with electronic	USPAT; EPO; JPO	2003/10/17 18:05
-	26	electromagnetic adj field and heat\$3 adj treat\$4 and inductive adj heat\$3	USPAT; EPO; JPO	2003/10/17 18:08
-	1	electromagnetic adj field and (electric\$2 circuit) with (component device) with treat\$4 and inductive adj heat\$3	USPAT; EPO; JPO	2003/10/17 18:10
-	92	electromagnetic adj field and (electric\$2 circuit) with (component device) and inductive adj heat\$3	USPAT; EPO; JPO	2003/10/17 18:10
-	18	4983804.URPN.	USPAT	2003/10/17 18:14
-	11	("2762892" "3467806" "4327265" "4431891" "4642442" "4659912" "4749833" "4771151" "4789767" "4795870" "4806107").PN.	USPAT	2003/10/17 18:17

US 20030115749	20030626	Inductive heating of microelectronic components	29/848	Chen, Jimmy Kuo
US 5958266 A	19990928	Method of plasma incision of matter with a specifically tuned radiofrequency electromagnetic field generated by a radio frequency oscillator	219/121.59	Fugo, Richard J. et al.
US 6278093 B1	20010821	Industrial apparatus to heat foodstuffs, particularly meat-products, by means of a radio frequency oscillator	219/601	Iacovacci, Vittorio et al.
US 6229131 B1	20010508	Microwave cooking grill and steamer	219/731	Koochaki, Kamel K.
US 5925455 A	19990720	Electromagnetic-power-absorbing composite comprising a crystalline ferromagnetic layer and a dielectric layer	428/328	Bruzzone, Charles L. et al.
US 5403376 A	19950404	Particle size distribution for controlling flow of metal powders melted to form electrical conductors	75/255	DeVolk, Gerald A. et al.
US 4503306 A	19850305	High frequency heating appliance	219/750	Nobue, Tomotaka et al.
US 3811940 A	19740521	HIGH FREQUENCY HEATING METHOD FOR VAPOR DEPOSITION OF COATINGS ONTO FILAMENTARY SUBSTRATES	227/595	Douglas, Frank C. et al.
WO 2054833 A1	20020711	IN APPLIANCE FOR THE EQUALISATION OF HEAT IN A DIELECTRIC LOAD HEATED BY AN OSCILLATING ELECTRIC FIELD	438/52	EKEMAR, LARS
US 6475822 B2	20021105	Method of making microelectronic contact structures	438/52	Eldridge, Benjamin N. et al.
US 6150186 A	20001121	Method of making a product with improved material properties by moderate heat-treatment of a metal	438/14	Chen, Jimmy Kuo-Wei et al.
US 6307161 B1	20011023	Partially-overcoated elongate contact structures	174/260	Grube, Gary W. et al.
US 6259155 B1	20010710	Polymer enhanced column grid array	257/690	Interrante, Mario John et al.
US 6184053 B1	20010206	Method of making microelectronic spring contact elements	438/52	Eldridge, Benjamin N. et al.
US 5912046 A	19990615	Method and apparatus for applying a layer of flowable coating material to a surface of an electronic component	427/126.2	Eldridge, Benjamin N. et al.
US 5476211 A	19951219	Method of manufacturing electrical contacts, using a sacrificial member	228/180.5	Khandros, Igor Y.
US 6035805 A	20000314	Method and apparatus for vacuum deposition of highly ionized media in an electromagnetic controlled reactor	118/723	Rust, Ray Dean
US 6590267 B1	20030708	Microelectromechanical flexible membrane electrostatic valve device and related fabrication methods	257/415	Goodwin-Johansson, So
US 6373682 B1	20020416	Electrostatically controlled variable capacitor	361/278	Goodwin-Johansson, So
US 6283829 B1	20010904	In situ friction detector method for finishing semiconductor wafers	451/8	Molnar, Charles J
US 6275320 B1	20010814	MEMS variable optical attenuator	359/237	Dhuler, Vijayakumar R. et al.
US 5938839 A	19990817	Method for forming a semiconductor device	117/104	Zhang, Hongyong
US 5928598 A	19990727	Method of making a microelectronic device package	264/446	Anderson, Michael John
US 5855686 A	19990105	Method and apparatus for vacuum deposition of highly ionized media in an electromagnetic controlled reactor	118/723	Rust, Ray Dean
US 5674742 A	19971007	Microfabricated reactor	435/286.5	Northrup, M. Allen et al.
US 5673139 A	19970930	Microelectromechanical television scanning device and method for making the same	359/291	Johnson, Michael D.
US 5417494 A	19950523	Contactless testing of electronic materials and devices using microwaves	374/5	Kempa, Krzysztof et al.
US 4355221 A	19821019	Method of field annealing an amorphous metal core by means of induction heating	148/108	Lin, Kou C.
US 4639279 A	19870127	Single frequency induction hardening process	148/573	Chatterjee, Madhu S.
US 4832763 A	19890523	Method of stress-relief annealing a magnetic core containing amorphous material	148/121	Rauch, Gary C. et al.
US 5695564 A	19971209	Semiconductor processing system	118/719	Imahashi, Issei
US 5609820 A	19970311	Apparatus for rendering medical materials safe	422/23	Bridges, Jack E. et al.
US 5175239 A	19921229	Process for making para-aramid fibers having high tenacity and modulus by microwave annealing	528/348	Gauntt, Sibbley P. et al.
US 4777336 A	19881011	Method for treating a material using radiofrequency waves	219/696	Asmussen, Jes
US 6548303 B2	20030415	Method and apparatus for rapid fat content determination	436/23	Collins, Michael J. et al.
US 6184509 B1	20010206	Heating apparatus and heating element assembly method	219/633	Scott, Gerald R. F. et al.
US 3759104 A	19730918	CAPACITANCE THERMOMETER	374/177	Robinson, Max C.

US 6508920 B1	20030121	Apparatus for low-temperature annealing of metallization microstructures in the production of a microelectronic device	Ritzdorf, Thomas L. et al.
US 5844216 A	19981201	System and apparatus for reducing arcing and localized heating during microwave processing	Fathi, Zakaryae et al.
US 6336269 B1	20020108	Method of fabricating an interconnection element	Eldridge, Benjamin N. et al.
US 6236491 B1	20010522	Micromachined electrostatic actuator with air gap	Goodwin-Johansson, Scott
US 6087266 A	20000711	Methods and apparatus for improving microloading while etching a substrate	Abraham, Susan C.
US 6004884 A	19991221	Methods and apparatus for etching semiconductor wafers	Abraham, Susan C.
US 5776359 A	19980707	Giant magnetoresistive cobalt oxide compounds	Schultz, Peter G. et al.
US 5773897 A	19980630	Flip chip monolithic microwave integrated circuit with mushroom-shaped, solder-capped, plated metal pads	Wen, Cheng P. et al.
US 5563182 A	19961008	Electromagnetic radiation absorbers and modulators comprising polyaniline	Epstein, Arthur J. et al.
US 5072087 A	19911210	Process for heating materials by microwave energy	Apte, Prasad S. et al.
US 6350973 B1	20020226	Radio-frequency and microwave-assisted processing of materials	Wroe, Fiona Catherine et al.
US 6229126 B1	20010508	Induction heating system with a flexible coil	Ulrich, Mark et al.
US 5710413 A	19980120	H-field electromagnetic heating system for fusion bonding	King, James D. et al.
US 5374809 A	19941220	Induction heating coupler and annealer	Fox, Robert L. et al.
US 5052997 A	19911001	Diathermy coil	Ruggera, Paul S.
US 6294401 B1	20010925	Nanoparticle-based electrical, chemical, and mechanical structures and methods of making same	Jacobson, Joseph M. et al.
US 6229124 B1	20010508	Inductive self-soldering printed circuit board	Trucco, Horacio Andres
US 5340428 A	19940823	Method for induction heating of composite material	Kodokian, George R.
US 4983804 A	19910108	Localized soldering by inductive heating	Chan, Hinghung A. et al.
US 4969968 A	19901113	Method of inductive heating with an integrated multiple particle agent	Leatherman, Alfred F.
US 4996405 A	19910226	Inductive heated portable hot plate	Pourmey, Michel et al.
US 5693875 A	19971202	Process for measuring the temperature of metallic workpieces and their solid content in a partially solidified material	Cremer, Ralf
US 4698473 A	19871006	Refractory metal-lined induction coil	Alcini, William V. et al.
US 6043563 A	20000328	Electronic components with terminals and spring contact elements extending from areas which are recessed in the components	Eldridge, Benjamin N. et al.